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NTD3817N

Power MOSFET 16 V, 34.5 A, Single N-Channel, DPAK/IPAK

Features

- Low $R_{DS(on)}$ to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Optimized Gate Charge to Minimize Switching Losses
- Three Package Variations for Design Flexibility
- These are Pb-Free Devices

Applications

- DC-DC Converters
- High Side Switching

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise stated)

| Parameter | Symbol | Value | Unit | | |
|--|--------------------------|--------------------------|------------------|----|---|
| Drain-to-Source Voltage | V_{DSS} | 16 | V | | |
| Gate-to-Source Voltage | V_{GS} | ± 16 | V | | |
| Continuous Drain Current $R_{\theta JA}$ (Note 1) | I_D | $T_A = 25^\circ\text{C}$ | 10.8 | | |
| | | $T_A = 85^\circ\text{C}$ | 8.4 | | |
| Power Dissipation $R_{\theta JA}$ (Note 1) | P_D | 2.5 | W | | |
| Continuous Drain Current $R_{\theta JA}$ (Note 2) | I_D | $T_A = 25^\circ\text{C}$ | 7.6 | | |
| | | $T_A = 85^\circ\text{C}$ | 5.9 | | |
| Power Dissipation $R_{\theta JA}$ (Note 2) | P_D | 1.2 | W | | |
| Continuous Drain Current $R_{\theta JC}$ (Note 1) | I_D | $T_C = 25^\circ\text{C}$ | 34.5 | | |
| | | $T_C = 85^\circ\text{C}$ | 26.8 | | |
| Power Dissipation $R_{\theta JC}$ (Note 1) | P_D | 25.9 | W | | |
| Pulsed Drain Current | $t_p = 10\mu\text{s}$ | $T_A = 25^\circ\text{C}$ | I_{DM} | 78 | A |
| Current Limited by Package | $T_A = 25^\circ\text{C}$ | $I_{DmaxPkg}$ | 22 | A | |
| Operating Junction and Storage Temperature | T_J, T_{STG} | -55 to +175 | $^\circ\text{C}$ | | |
| Source Current (Body Diode) | I_S | 21.6 | A | | |
| Drain to Source dV/dt | dV/dt | 6 | V/ns | | |
| Single Pulse Drain-to-Source Avalanche Energy ($T_J = 25^\circ\text{C}$, $V_{DD} = 50\text{ V}$, $V_{GS} = 10\text{ V}$, $I_L = 10\text{ A}_{pk}$, $L = 0.3\text{ mH}$, $R_G = 25\ \Omega$) | EAS | 15 | mJ | | |
| Lead Temperature for Soldering Purposes (1/8" from case for 10 s) | T_L | 260 | $^\circ\text{C}$ | | |

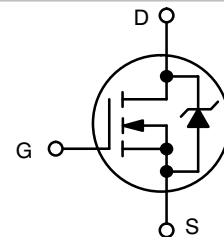
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



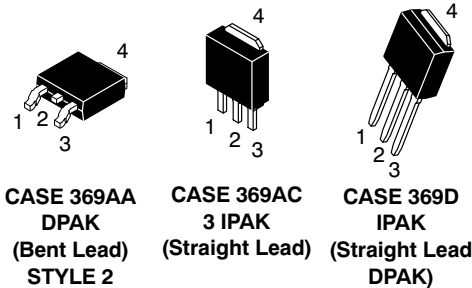
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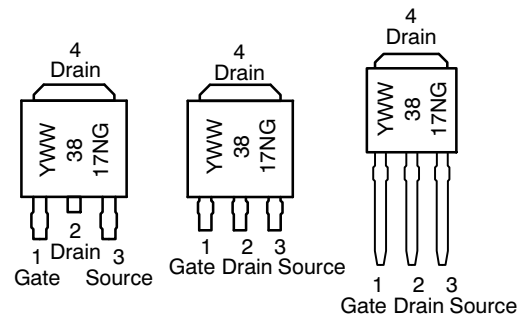
| $V_{(BR)DSS}$ | $R_{DS(ON)}$ MAX | I_D MAX |
|---------------|------------------------|-----------|
| 16 V | 13.9 m Ω @ 10 V | 34.5 A |
| | 29 m Ω @ 4.5 V | |



N-CHANNEL MOSFET



MARKING DIAGRAMS & PIN ASSIGNMENTS



Y = Year
 WW = Work Week
 3817N = Device Code
 G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

NTD3817N

THERMAL RESISTANCE MAXIMUM RATINGS

| Parameter | Symbol | Value | Unit |
|---|---------------------|-------|------|
| Junction-to-Case (Drain) | $R_{\theta JC}$ | 5.8 | °C/W |
| Junction-to-TAB (Drain) | $R_{\theta JC-TAB}$ | 4.5 | |
| Junction-to-Ambient – Steady State (Note 1) | $R_{\theta JA}$ | 59 | |
| Junction-to-Ambient – Steady State (Note 2) | $R_{\theta JA}$ | 121 | |

1. Surface-mounted on FR4 board using 1 sq-in pad, 1 oz Cu.
2. Surface-mounted on FR4 board using the minimum recommended pad size.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|-----------|--------|----------------|-----|-----|-----|------|
|-----------|--------|----------------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | | |
|---|-------------------|---|---------------------------|------|-----------|---------------|
| Drain-to-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$ | 16 | | | V |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | $V_{(BR)DSS}/T_J$ | | | 15.5 | | mV/°C |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{GS} = 0\text{ V}, V_{DS} = 16\text{ V}$ | $T_J = 25^\circ\text{C}$ | | 1.0 | μA |
| | | | $T_J = 125^\circ\text{C}$ | | 10 | |
| Gate-to-Source Leakage Current | I_{GSS} | $V_{DS} = 0\text{ V}, V_{GS} = \pm 16\text{ V}$ | | | ± 100 | nA |

ON CHARACTERISTICS (Note 3)

| | | | | | | | |
|--|------------------|--|---------------------|-----|------|-------|------------|
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{GS} = V_{DS}, I_D = 250\ \mu\text{A}$ | 1.5 | | 2.5 | V | |
| Negative Threshold Temperature Coefficient | $V_{GS(TH)}/T_J$ | | | 5.1 | | mV/°C | |
| Drain-to-Source On Resistance | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}$ | $I_D = 15\text{ A}$ | | 12.8 | 13.9 | m Ω |
| | | $V_{GS} = 4.5\text{ V}$ | $I_D = 15\text{ A}$ | | 19.2 | 29 | |
| Forward Transconductance | g_{FS} | $V_{DS} = 1.5\text{ V}, I_D = 15\text{ A}$ | | 28 | | S | |

CHARGES AND CAPACITANCES

| | | | | | | |
|------------------------------|--------------|--|--|------|------|----|
| Input Capacitance | C_{ISS} | $V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}, V_{DS} = 12\text{ V}$ | | 702 | | pF |
| Output Capacitance | C_{OSS} | | | 257 | | |
| Reverse Transfer Capacitance | C_{RSS} | | | 168 | | |
| Total Gate Charge | $Q_{G(TOT)}$ | $V_{GS} = 4.5\text{ V}, V_{DS} = 12\text{ V}, I_D = 15\text{ A}$ | | 7.0 | 10.5 | nC |
| Threshold Gate Charge | $Q_{G(TH)}$ | | | 0.6 | | |
| Gate-to-Source Charge | Q_{GS} | | | 2.5 | | |
| Gate-to-Drain Charge | Q_{GD} | | | 3.5 | | |
| Total Gate Charge | $Q_{G(TOT)}$ | $V_{GS} = 10\text{ V}, V_{DS} = 12\text{ V}, I_D = 15\text{ A}$ | | 13.5 | | nC |

SWITCHING CHARACTERISTICS (Note 4)

| | | | | | | |
|---------------------|--------------|---|--|-----|--|----|
| Turn-On Delay Time | $t_{d(ON)}$ | $V_{GS} = 4.5\text{ V}, V_{DS} = 12\text{ V}, I_D = 15\text{ A}, R_G = 3.0\ \Omega$ | | 12 | | ns |
| Rise Time | t_r | | | 50 | | |
| Turn-Off Delay Time | $t_{d(OFF)}$ | | | 12 | | |
| Fall Time | t_f | | | 4.6 | | |
| Turn-On Delay Time | $t_{d(ON)}$ | $V_{GS} = 10\text{ V}, V_{DS} = 12\text{ V}, I_D = 15\text{ A}, R_G = 3.0\ \Omega$ | | 8.0 | | ns |
| Rise Time | t_r | | | 47 | | |
| Turn-Off Delay Time | $t_{d(OFF)}$ | | | 20 | | |
| Fall Time | t_f | | | 10 | | |

3. Pulse Test: pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.
4. Switching characteristics are independent of operating junction temperatures.
5. Assume standoff of 110 mm

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|-----------|--------|----------------|-----|-----|-----|------|
|-----------|--------|----------------|-----|-----|-----|------|

DRAIN-SOURCE DIODE CHARACTERISTICS

| | | | | | | | |
|-------------------------|----------|---|---------------------------|--|------|-----|----|
| Forward Diode Voltage | V_{SD} | $V_{GS} = 0\text{ V},$ $I_S = 15\text{ A}$ | $T_J = 25^\circ\text{C}$ | | 0.96 | 1.1 | V |
| | | | $T_J = 125^\circ\text{C}$ | | 0.86 | | |
| Reverse Recovery Time | t_{RR} | $V_{GS} = 0\text{ V},$ $dI_S/dt = 100\text{ A}/\mu\text{s},$ $I_S = 15\text{ A}$ | | | 11 | | ns |
| Charge Time | t_a | | | | 5.4 | | |
| Discharge Time | t_b | | | | 5.6 | | |
| Reverse Recovery Charge | Q_{RR} | | | | 2.8 | | |

PACKAGE PARASITIC VALUES

| | | | | | | |
|---------------------------------|-------|--------------------------|--|--------|--|----|
| Source Inductance | L_S | $T_A = 25^\circ\text{C}$ | | 2.49 | | nH |
| Drain Inductance, DPAK | L_D | | | 0.0164 | | |
| Drain Inductance, IPAK (Note 5) | L_D | | | 1.88 | | |
| Gate Inductance | L_G | | | 3.46 | | |
| Gate Resistance | R_G | | | 1.0 | | |

3. Pulse Test: pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.
4. Switching characteristics are independent of operating junction temperatures.
5. Assume standoff of 110 mm

TYPICAL PERFORMANCE CURVES

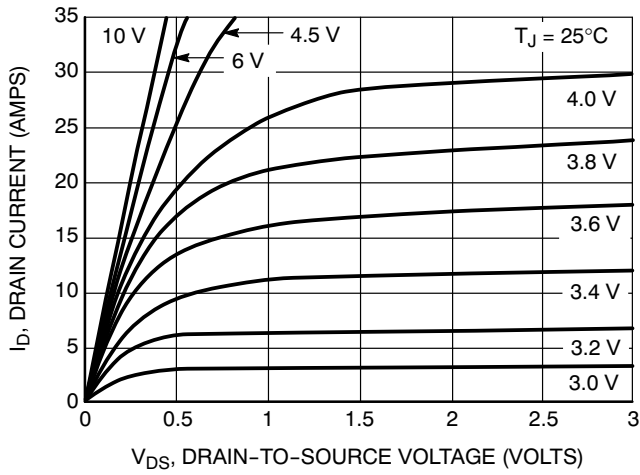


Figure 1. On-Region Characteristics

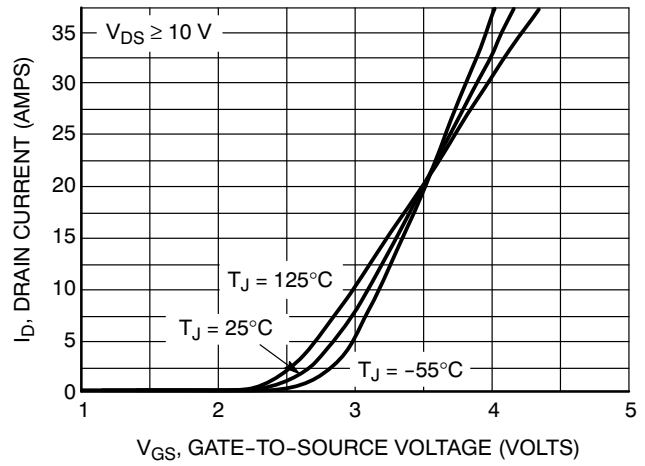


Figure 2. Transfer Characteristics

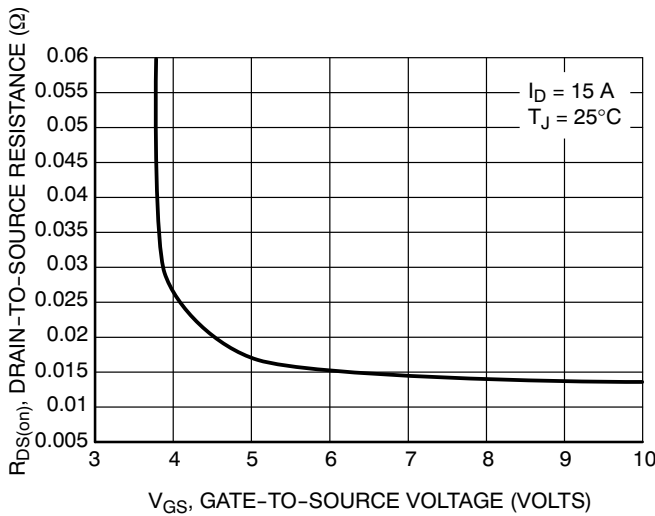


Figure 3. On-Resistance vs. Gate-to-Source Voltage

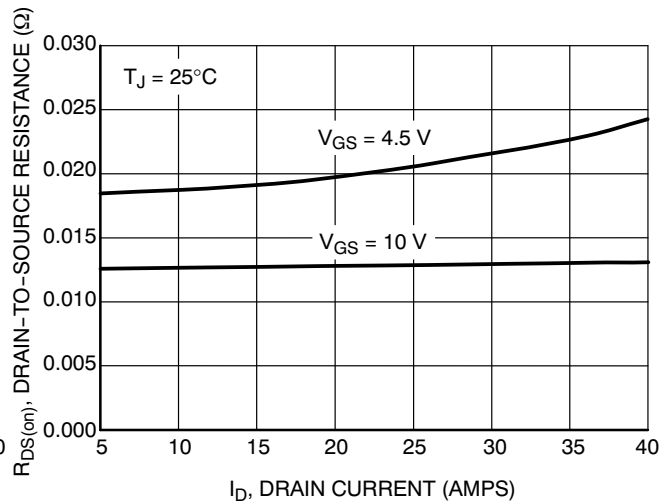


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

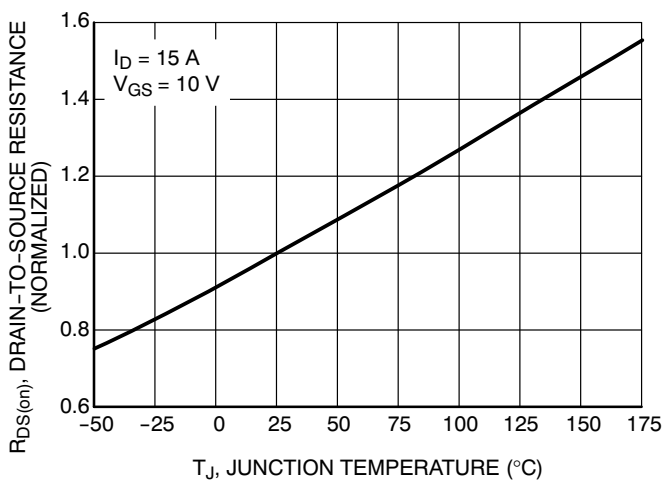


Figure 5. On-Resistance Variation with Temperature

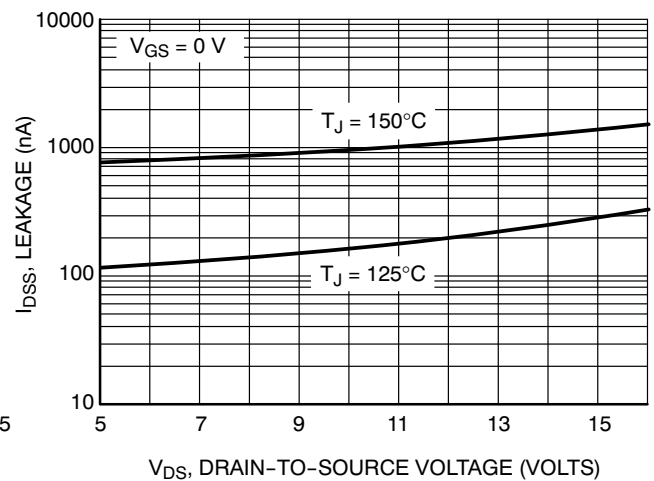


Figure 6. Drain-to-Source Leakage Current vs. Drain Voltage

TYPICAL PERFORMANCE CURVES

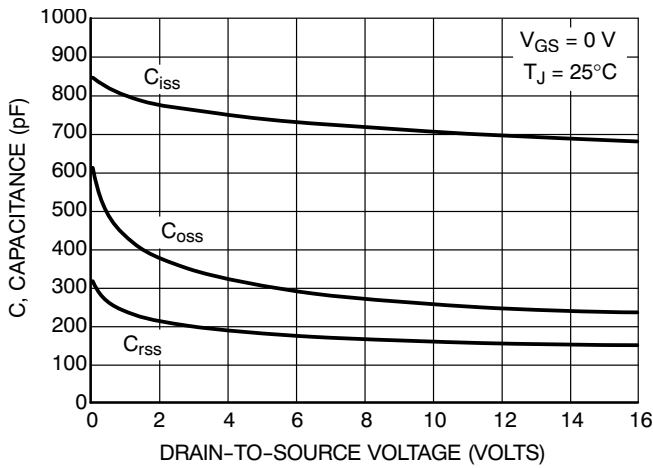


Figure 7. Capacitance Variation

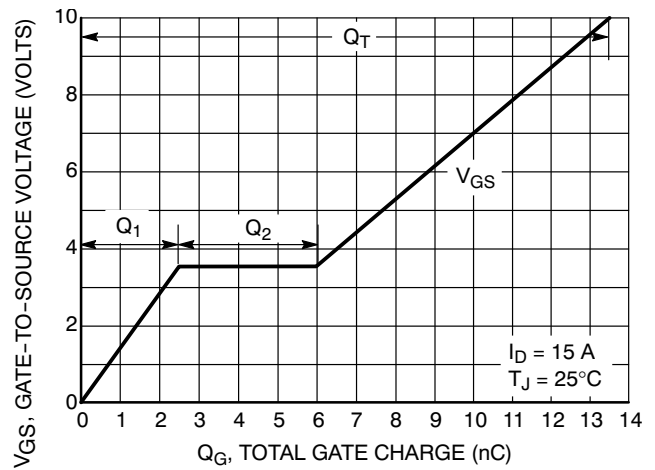


Figure 8. Gate-To-Source and Drain-To-Source Voltage vs. Total Charge

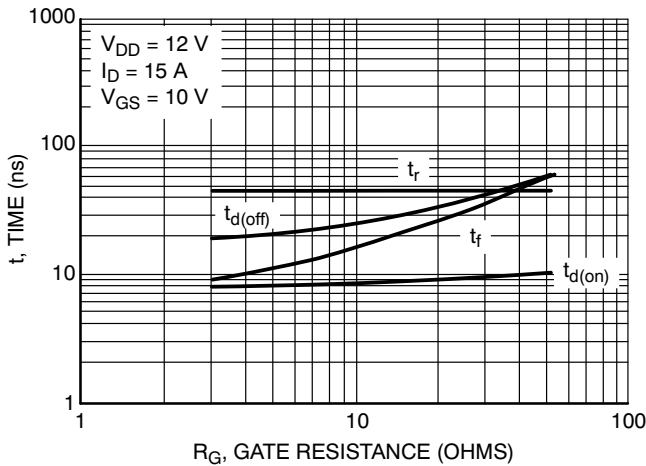


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

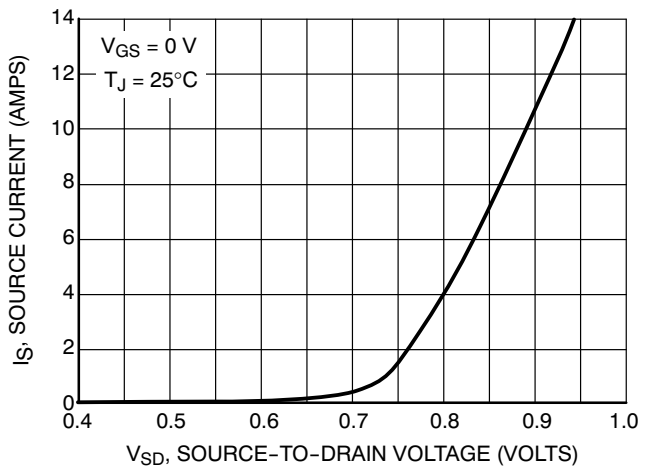


Figure 10. Diode Forward Voltage vs. Current

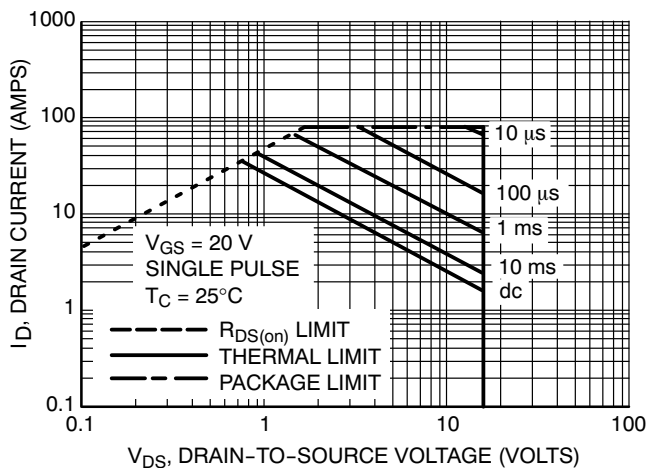


Figure 11. Maximum Rated Forward Biased Safe Operating Area

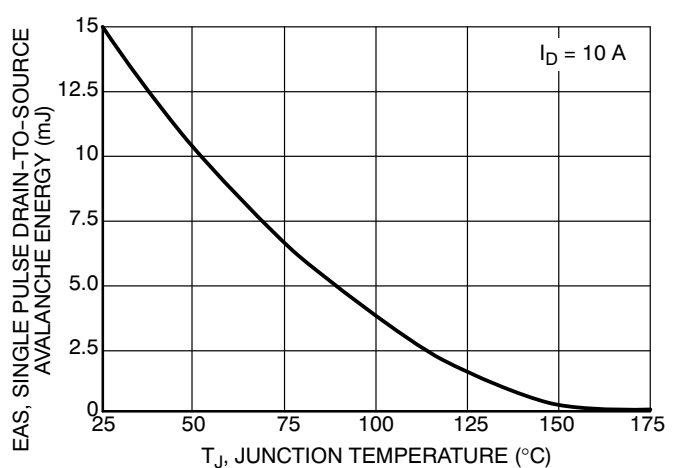


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

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ORDERING INFORMATION

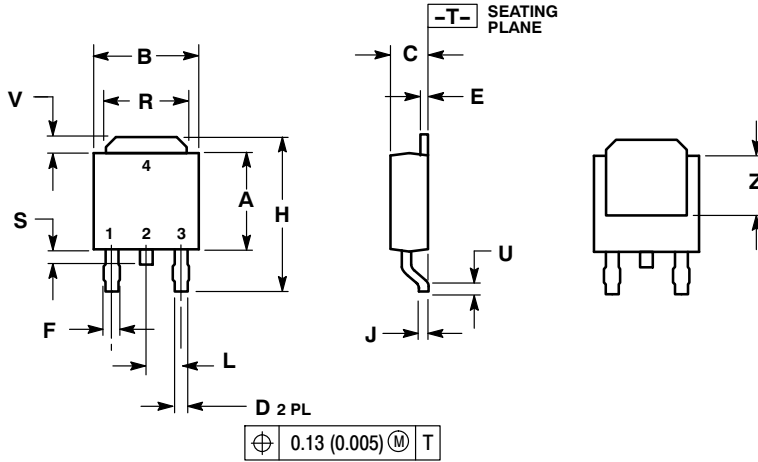
| Device | Package | Shipping† |
|--------------|---|--------------------|
| NTD3817NT4G | DPAK (Pb-Free) | 2500 / Tape & Reel |
| NTD3817N-1G | IPAK (Pb-Free) | 75 Units / Rail |
| NTD3817N-35G | IPAK Trimmed Lead (3.5 ± 0.15 mm) (Pb-Free) | 75 Units / Rail |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE) CASE 369AA-01 ISSUE A

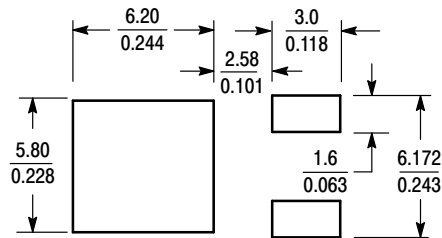


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

| DIM | INCHES | | MILLIMETERS | |
|-----|-----------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.235 | 0.245 | 5.97 | 6.22 |
| B | 0.250 | 0.265 | 6.35 | 6.73 |
| C | 0.086 | 0.094 | 2.19 | 2.38 |
| D | 0.025 | 0.035 | 0.63 | 0.89 |
| E | 0.018 | 0.024 | 0.46 | 0.61 |
| F | 0.030 | 0.045 | 0.77 | 1.14 |
| H | 0.386 | 0.410 | 9.80 | 10.40 |
| J | 0.018 | 0.023 | 0.46 | 0.58 |
| L | 0.090 BSC | | 2.29 BSC | |
| R | 0.180 | 0.215 | 4.57 | 5.45 |
| S | 0.024 | 0.040 | 0.60 | 1.01 |
| U | 0.020 | --- | 0.51 | --- |
| V | 0.035 | 0.050 | 0.89 | 1.27 |
| Z | 0.155 | --- | 3.93 | --- |

- STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

SOLDERING FOOTPRINT*



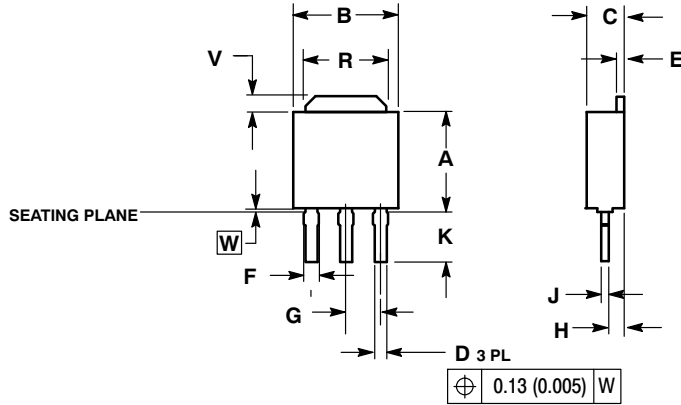
SCALE 3:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

3 IPAK, STRAIGHT LEAD CASE 369AC-01 ISSUE O

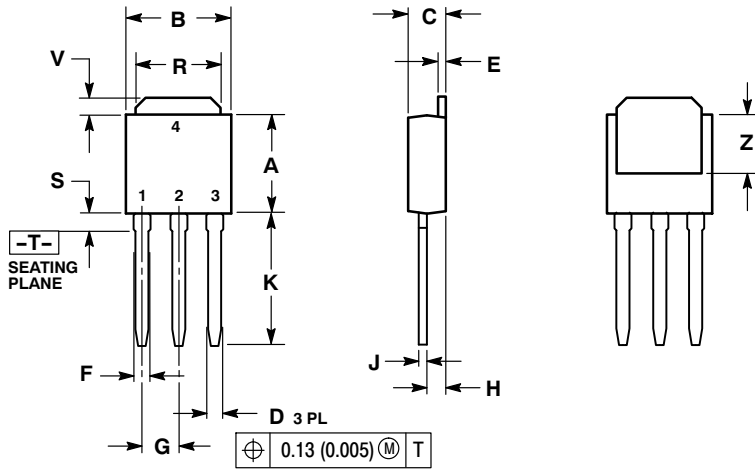


NOTES:

- 1.. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2.. CONTROLLING DIMENSION: INCH.
3. SEATING PLANE IS ON TOP OF DAMBAR POSITION.
4. DIMENSION A DOES NOT INCLUDE DAMBAR POSITION OR MOLD GATE.

| DIM | INCHES | | MILLIMETERS | |
|-----|-----------|-------|-------------|------|
| | MIN | MAX | MIN | MAX |
| A | 0.235 | 0.245 | 5.97 | 6.22 |
| B | 0.250 | 0.265 | 6.35 | 6.73 |
| C | 0.086 | 0.094 | 2.19 | 2.38 |
| D | 0.027 | 0.035 | 0.69 | 0.88 |
| E | 0.018 | 0.023 | 0.46 | 0.58 |
| F | 0.037 | 0.043 | 0.94 | 1.09 |
| G | 0.090 BSC | | 2.29 BSC | |
| H | 0.034 | 0.040 | 0.87 | 1.01 |
| J | 0.018 | 0.023 | 0.46 | 0.58 |
| K | 0.134 | 0.142 | 3.40 | 3.60 |
| R | 0.180 | 0.215 | 4.57 | 5.46 |
| V | 0.035 | 0.050 | 0.89 | 1.27 |
| W | 0.000 | 0.010 | 0.000 | 0.25 |

IPAK (STRAIGHT LEAD DPAK) CASE 369D-01 ISSUE B



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

| DIM | INCHES | | MILLIMETERS | |
|-----|-----------|-------|-------------|------|
| | MIN | MAX | MIN | MAX |
| A | 0.235 | 0.245 | 5.97 | 6.35 |
| B | 0.250 | 0.265 | 6.35 | 6.73 |
| C | 0.086 | 0.094 | 2.19 | 2.38 |
| D | 0.027 | 0.035 | 0.69 | 0.88 |
| E | 0.018 | 0.023 | 0.46 | 0.58 |
| F | 0.037 | 0.045 | 0.94 | 1.14 |
| G | 0.090 BSC | | 2.29 BSC | |
| H | 0.034 | 0.040 | 0.87 | 1.01 |
| J | 0.018 | 0.023 | 0.46 | 0.58 |
| K | 0.350 | 0.380 | 8.89 | 9.65 |
| R | 0.180 | 0.215 | 4.45 | 5.45 |
| S | 0.025 | 0.040 | 0.63 | 1.01 |
| V | 0.035 | 0.050 | 0.89 | 1.27 |
| Z | 0.155 | --- | 3.93 | --- |

STYLE 2:

1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

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